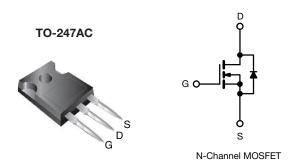
www.vishay.com

Vishay Siliconix

HALOGEN

FREE

EF Series Power MOSFET With Fast Body Diode



PRODUCT SUMMARY				
V _{DS} (V) at T _J max.	650			
R _{DS(on)} typ. (Ω) at 25 °C	V _{GS} = 10 V	0.059		
Q _g max. (nC)	77			
Q _{gs} (nC)	19			
Q _{gd} (nC)	16			
Configuration	Single			

FEATURES

- 4th generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- · Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Motor drives
 - Battery chargers
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	TO-247AC
Lead (Pb)-free and halogen-free	SiHG068N60EF-GE3

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise parameter			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V _{DS}	600	\/	
Gate-source voltage			V_{GS}	± 30	V	
Continuous drain current (T _J = 150 °C)	V _{GS} at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$		41	А	
	V _{GS} at 10 V	T _C = 100 °C	I _D	26		
Pulsed drain current ^a			I _{DM}	115		
Linear derating factor				2	W/°C	
Single pulse avalanche energy b			E _{AS}	226	mJ	
Maximum power dissipation			P _D	250	W	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C		
Drain-source voltage slope	$T_{J} = $	T _J = 125 °C		70	1//20	
leverse diode dV/dt d		dV/dt	50	V/ns		
Soldering recommendations (peak temperature)	For	For 10 s		260	°C	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 120 V, starting T_J = 25 °C, L = 28.2 mH, R_q = 25 Ω , I_{AS} = 4 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, di/dt = 210 A/ μ s, starting $T_J = 25$ °C



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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	LIMIT	UNIT		
Maximum junction-to-ambient	R _{thJA}	40	°C/W		
Maximum junction-to-case (drain)	R _{thJC}	0.5	C/VV		

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I _D = 1 mA		-	0.63	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		3	-	5	V
		,	$V_{GS} = \pm 20 \text{ V}$		-	± 100	nA
Gate-source leakage	I _{GSS}	,	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
Zava gata valtaga duain ayuwant		V _{DS} =	$V_{DS} = 480 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 480 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 125 ^{\circ}\text{C}$		-	1	μΑ
Zero gate voltage drain current	I _{DSS}	V _{DS} = 480 V			-	2	mA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 16 A	-	0.059	0.068	Ω
Forward transconductance	9 _{fs}	V _{DS} = 30 V, I _D = 16 A		-	9	-	S
Dynamic							
Input capacitance	C _{iss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ $f = 1 \text{ MHz}$		-	2628	-	pF
Output capacitance	C _{oss}			-	122	-	
Reverse transfer capacitance	C _{rss}			-	7	-	
Effective output capacitance, energy related ^a	C _{o(er)}	V 0.VI 400.V V 0.V		-	87	-	
Effective output capacitance, time related ^b	C _{o(tr)}	V _{DS} = 0 \	$V_{DS} = 0 \text{ V to } 480 \text{ V}, V_{GS} = 0 \text{ V}$		543	-	
Total gate charge	Qg			-	51	77	
Gate-source charge	Q _{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 16 \text{ A}, V_{DS} = 480 \text{ V}$	-	19	-	nC
Gate-drain charge	Q _{gd}	7		-	16	-	
Turn-on delay time	t _{d(on)}			-	27	54	
Rise time	t _r	$V_{DD} = 480 \text{ V}, I_{D} = 16 \text{ A},$ $V_{GS} = 10 \text{ V}, R_{g} = 9.1 \Omega$		-	55	83	ns
Turn-off delay time	t _{d(off)}			-	53	80	
Fall time	t _f			-	35	70	
Gate input resistance	R_g	f = 1 MHz, open drain		0.3	0.7	1.4	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	41	^
Pulsed diode forward current	I _{SM}			-	-	115	- A
Diode forward voltage	V_{SD}	T _J = 25 °C, I _S = 16 A, V _{GS} = 0 V		-	-	1.2	V
Reverse recovery time	t _{rr}	$T_J = 25 \text{ °C}, I_F = I_S = 16 \text{ A},$ $di/dt = 100 \text{ A/µs}, V_R = 400 \text{ V}$		-	152	304	ns
Reverse recovery charge	Q _{rr}			-	1	2	μC
Reverse recovery current	I _{RRM}			-	14	-	Α

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}

b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

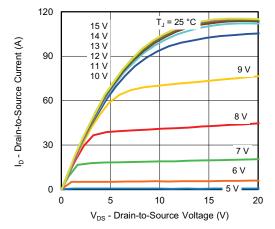


Fig. 1 - Typical Output Characteristics

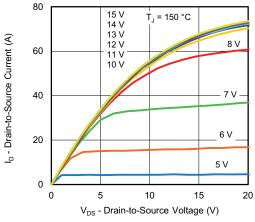


Fig. 2 - Typical Output Characteristics

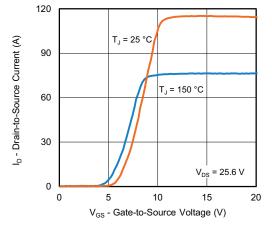


Fig. 3 - Typical Transfer Characteristics

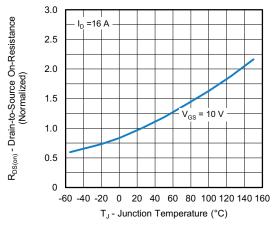


Fig. 4 - Normalized On-Resistance vs. Temperature

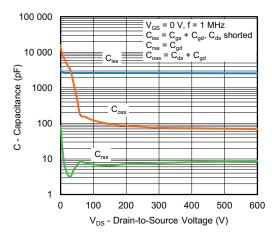


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

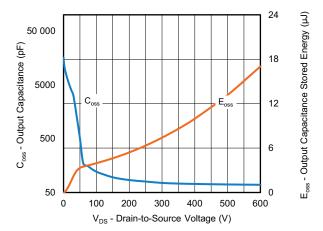


Fig. 6 - Coss and Eoss vs. VDS



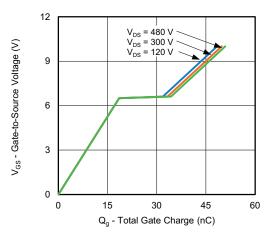


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

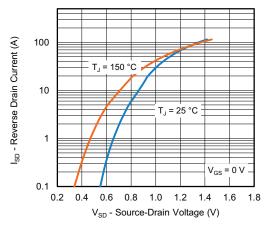


Fig. 8 - Typical Source-Drain Diode Forward Voltage

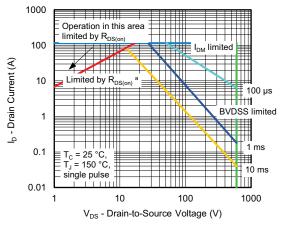


Fig. 9 - Maximum Safe Operating Area

Note

a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

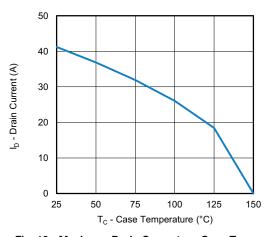


Fig. 10 - Maximum Drain Current vs. Case Temperature

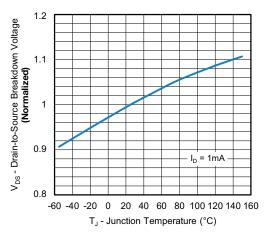


Fig. 11 - Temperature vs. Drain-to-Source Voltage



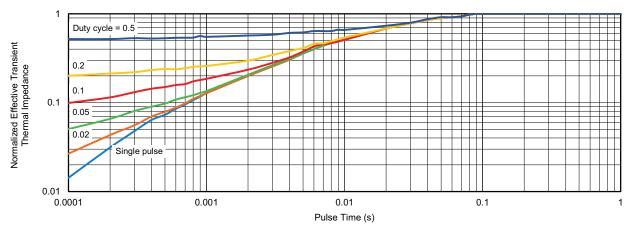


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

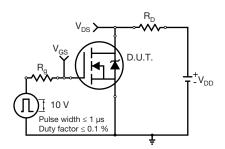


Fig. 13 - Switching Time Test Circuit

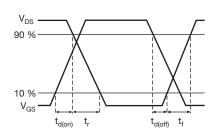


Fig. 14 - Switching Time Waveforms

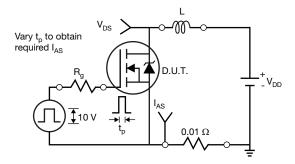


Fig. 15 - Unclamped Inductive Test Circuit

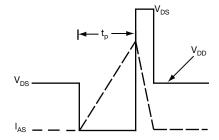


Fig. 16 - Unclamped Inductive Waveforms

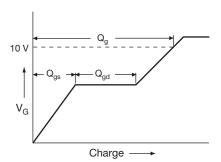


Fig. 17 - Basic Gate Charge Waveform

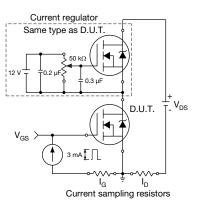
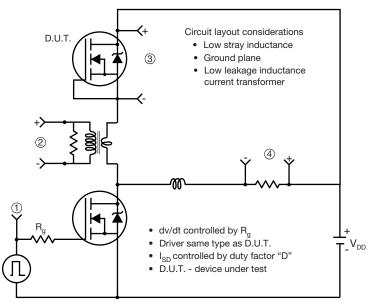


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit



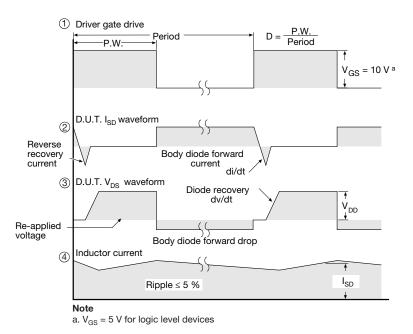


Fig. 19 - For N-Channel

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